ABSTRACT OF THE DISCLOSURE

TAB TAPE WITH STIFFENER AND SEMICONDUCTOR DEVICE USING SAME

A TAB tape with a stiffener is prepared by bonding a one-metal TAB tape 20 having a structure wherein a circuit pattern 21 is formed on either surface of a first tape base material, a part thereof is covered with an insulating film 2, and a via hole 12 is defined on a connecting regional section 25 for via, to a tape 30 for second metal prepared by providing a metallic foil layer 14 on either surface of a second tape base material 15 through an adhesive layer 15; the connecting regional section 25 for via on the upper edge of a via hole is electrically connected with a part of the metallic foil layer 14 on the bottom of the hole by means of conducting means (4, 16, and 18), and at the same time, an exposed portion 32 of the metallic foil layer 14, which has not been covered with the one-metal TAB tape 20, is connected to an electrode 71 of a ground line in the semiconductor 7 by means of a bonding wire 83 to lead a ground potential. Thus, an inexpensive TAB tape with a stiffener having equivalent electrical characteristics to that in the case where a conventional two-metal and one-base material TAB tape is used, and a TBGA semiconductor device using such TAB tape with a stiffener is obtained.

(Figure 1)